SPECIFICATION

COMMERCIALLY AVAILABLE

ITEM: SAW FILTER

PART NUMBER: SF0204004

ISSUED / REVISION	ENGINEER APPROVED	DOCUMENT CHECKED	DRAFTSMAN
1/12/2011 DS			
1/17/11 DS	**1/17/2011 SRJ**	1/17/2011 BF	**1/17/2011 GL**
1/20/11 DS	**1/21/2011 SRJ**	1/24/2011 BF	**1/24/2011 GL**

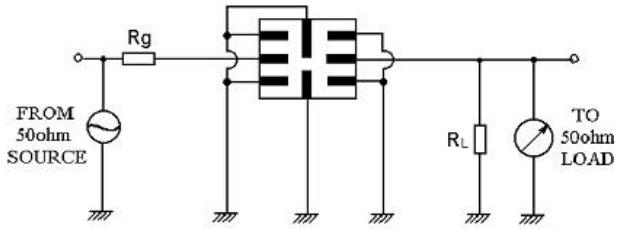
***FILTRO**NETICS Inc*

1. Electrical Specifications:

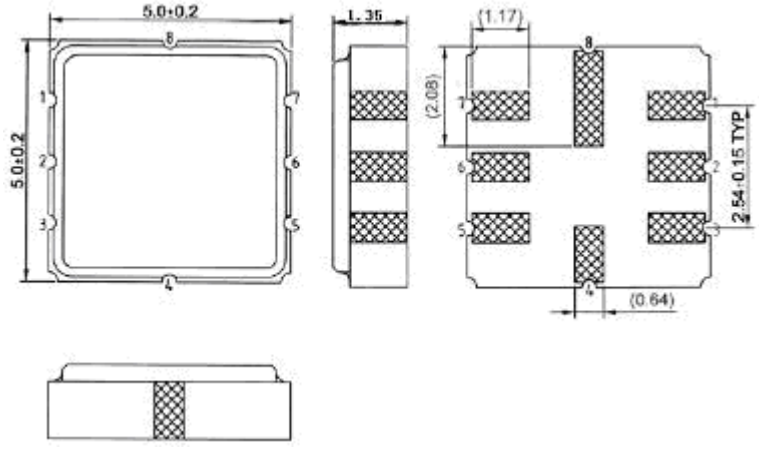
PART NUMBER	SF0204004	UNIT
NOMINAL CENTER FREQUENCY(Fo)	204.8	MHz
INSERTION LOSS: 1. Fo -100 MHz TO -42.8 MHz 2. Fo ±2 MHz 3. Fo +42.8 TO Fo +100MHz	 50.0 MIN 5.5 MAX 50.0 MIN	dB
RIPPLE (Fo ±2 MHz)	2.0 MAX	dB
INPUT AND OUTPUT IMPEDANCE	50/0	Ω/pF

DC Voltage VDC	10V
AC Voltage Vpp	10V 50Hz/60Hz
Operation Temperature	-20°C to +85°C
Storage Temperature	-45°C to +85°C
RF Power Dissipation	0 dBm

TEST CIRCUIT

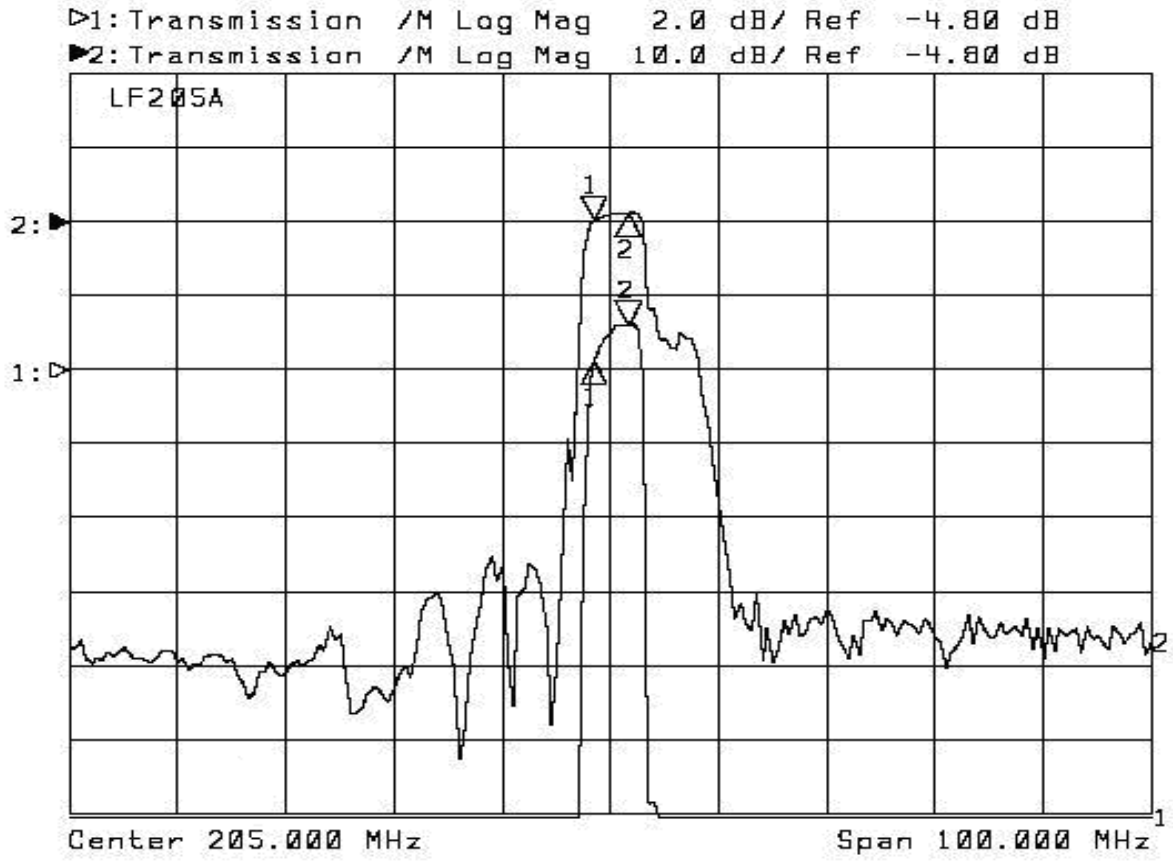


2: Mechanical:



1. Ground
2. Input/output
3. Ground
4. Ground
5. Ground
6. Input/output
7. Ground
8. Ground

3:Plot



4. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -25 for 30 minutes. Following by a high temperature of +25 for 5 Minutes and a higher temperature of +85 for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2-2.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260 ±5 for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2-2.

5-3 Solderability

Submerge the device terminals into the solder bath at 245 ±5 for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2-2.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2-2.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2-2.

5. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

6. Packing

7.1 Dimensions

(1) Carrier Tape: Figure 1

(2) Reel: Figure 2

(3) The product shall be packed properly not to be damaged during transportation and storage.

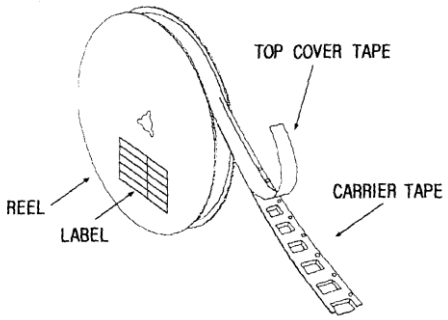
7.2 Reeling Quantity

1000 pcs/reel 7’’

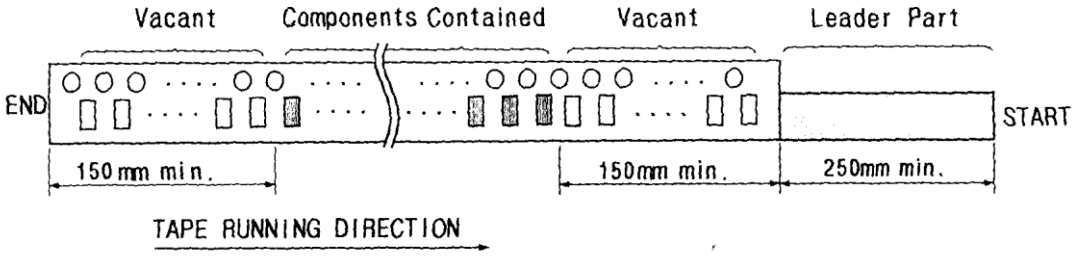
3000 pcs/reel 13’’

7.3 Taping Structure

(1) The tape shall be wound around the reel in the direction shown below.



(3) Leader part and vacant position specifications.



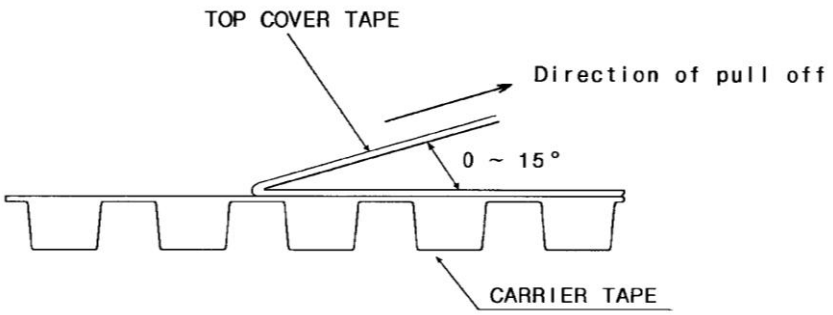
7. TAPE SPECIFICATIONS

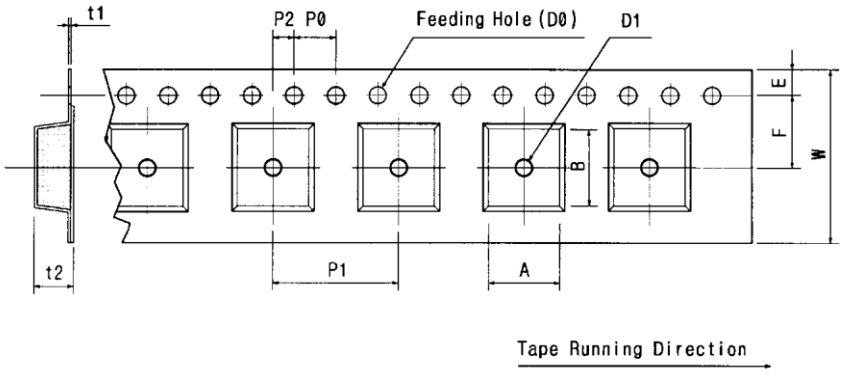
8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

8.2 Top Cover Tape Adhesion (See the below figure)

(1) Pull off angle: 0~15º
(2) Speed: 300mm/min.
(3) Force: 20~70g

[Figure 1] Carrier Tape Dimensions



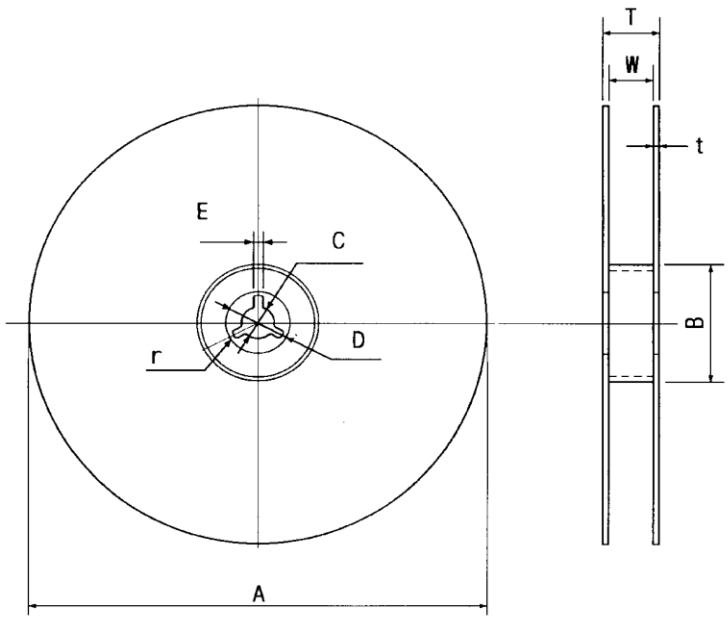


[Unit: mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.0±0.3	5.5 ±0.05	1.75±0.1	4.0 ±0.1	8.0 ±0.1	2.0 ±0.05	Ø1.5±0.1	Ø1.0 ±0.25	0.3 ±0.05	2.10±0.1	6.40±0.1	5.20±0.1

[Unit: mm]

[Figure 2]



A	B	C	D	E	W	t	r
Ø330 ±1.0	Ø100 ±0.5	Ø13 ±0.5	Ø21 ±0.8	2 ±0.5	13 ±0.3	3 max.	1.0 max.